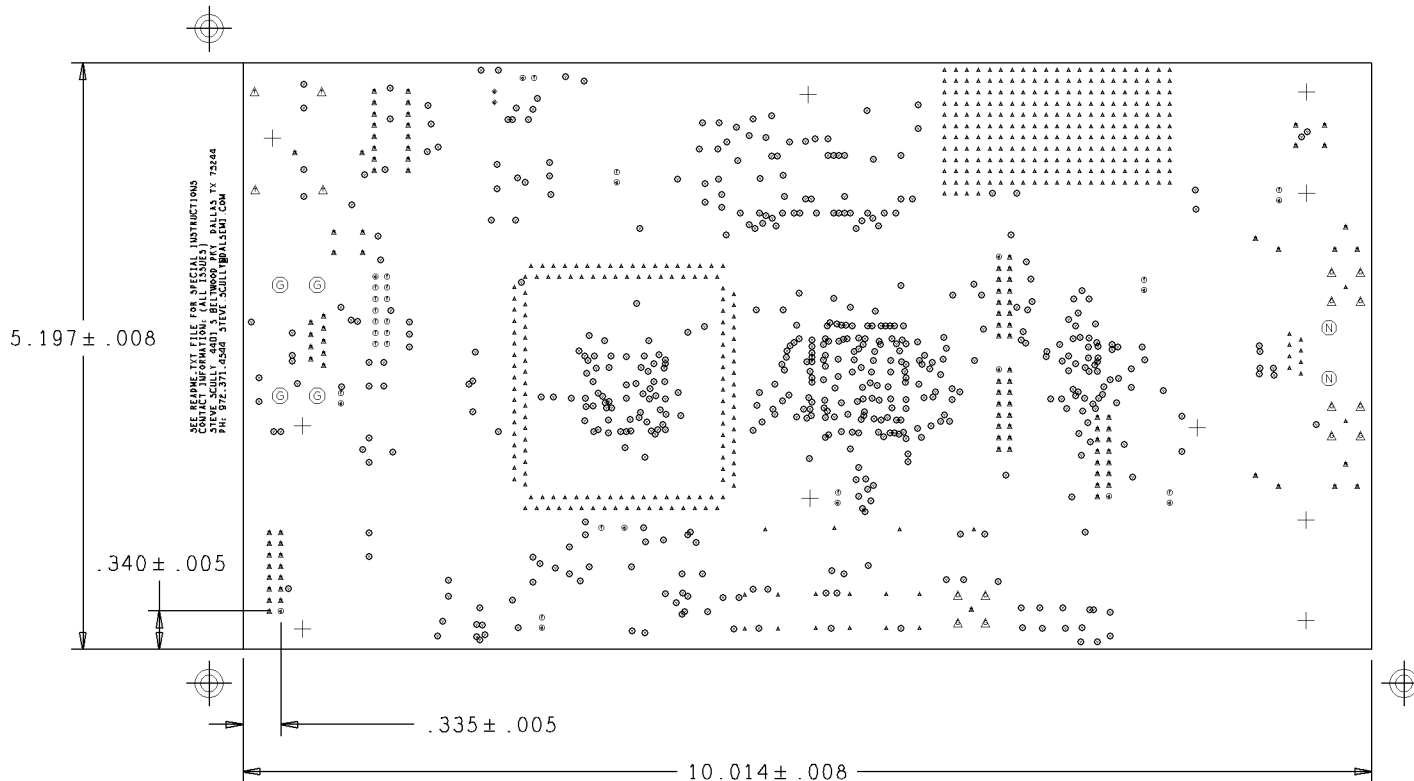


NOTES:

1. SILK SCREEN TOP AND BOTTOM USING WHITE NON-CONDUCTIVE INK.
2. COPPER EXTERNAL/INTERNAL 0.5 OUNCE. EXTERNAL PLATED TO 1 OUNCE.
3. HOLE SIZES ARE FINISHED SIZE.
4. FINISH: LPI SOLDERMASK, COLOR BLUE, WITH EXPOSED COPPER AREAS PLATED WITH STANDARD 3-8 MICROINCHES IMMERSION GOLD OVER 100 MINIMUM MICROINCHES ELECTROLESS NICKEL.
5. MATERIAL FR4, DIELECTRIC CONSTANT 4.5.
6. BUILD/MANUFACTURE TO BEST COMMERCIAL STANDARDS.
7. BOARD THICKNESS .084 +/- 10%.
8. TOP LAYER TO LAYER 2 DIELECTRIC THICKNESS .013 +/- 10%.
9. BOTTOM LAYER TO LAYER 5 DIELECTRIC THICKNESS .013 +/- 10%.
10. ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE SPECIFIED.



HOLE CHART				
ALL UNITS ARE IN INCHES				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
○	0.010	+0/- .010	PLATED	528
+	0.030	+/-0.003	PLATED	2
△	0.036	+/-0.003	PLATED	405
◉	0.041	+/-0.003	PLATED	21
⊙	0.042	+/-0.003	PLATED	14
▲	0.048	+/-0.003	PLATED	106
△	0.071	+/-0.003	PLATED	4
△	0.075	+/-0.003	PLATED	8
△	0.085	+/-0.003	PLATED	4
+	0.120	+/-0.003	PLATED	10
(N)	0.130	+/-0.003	NON-PLATED	2
⊙	0.140	+/-0.003	NON-PLATED	4

DALLAS SEMICONDUCTOR 2005
DS26502DK01B0
FABRICATION DRAWING